IPC ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information			
Supplier 1	Information								·					
Company name* Company unique ID				nique ID	ID Unique J		Jnique ID Auth	nique ID Authority			Response Date*			
nsemi											2023-06-08			
Contact Nai	me		Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-En	ıv-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title -				itle - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Con				iro Compliance	o Compliance NA		NA			Product-Env-Stewards@onsemi.com				
]	Requester Item Number	Mfr Item	Number Mfr Item Name				Effective Date	Version	rsion Manufacturing Site		W	eight*	UOM	Unit Type
	FXGL2014MTCX QUA		QUAD 2-INPUT EX OR			2023-06-08		Т	TAD		.8492	mg	Each	
	turing Proccess Inform												·	·
Terminal Plating / Grid Array Material Terminal Base						Peak Process Body Temperature Max Time at Peak Tem				Temperatur	e Numb	er of Reflow Cyc	eles	
N	Matte Tin (Sn) - annealed	C	CU Alloy	1			260		C	30	seconds	3		
omments														
vel 1 - max	ximum time at peak tempera	ture during sol	dering is 10-3	30 seconds										
or more in	formation regarding materia	al composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.327	mg	Supplier	Silicon (Si)	7440-21-3		0.327	mg
Die Attach	0.903	mg		Epoxy resin	proprietary data		0.0903	mg
			Supplier	Silver (Ag)	7440-22-4		0.7224	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0903	mg
Lead Frame	21.12	mg	Supplier	Silver (Ag)	7440-22-4		0.6357	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0317	mg
			Supplier	Silicon (Si)	7440-21-3		0.1373	mg
			В	Nickel (Ni)	7440-02-0		0.6336	mg
			Supplier	Copper (Cu)	7440-50-8		19.6817	mg
Mold Compound-Black	42.4542	mg		Epoxy resin	proprietary data		2.1227	mg
			Supplier	Phenol Resin	Proprietary Data		1.6982	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.2454	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4245	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		33.9634	mg
Plating	2.0	mg	Supplier	Tin (Sn)	7440-31-5		2	mg
Wire Bond	0.045	mg	Supplier	Palladium (Pd)	7440-05-3		0.0005	mg
			Supplier	Copper (Cu)	7440-50-8		0.0446	mg